

DATE 29 FEB 2012

ASIES.

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

2. CONTROLLING DIMENSION: MILLIMETERS.

3. DATUM C IS THE SEATING PLANE.

0.15

1.30

0.26

3.00

3.10

1.80 0.95 BSC

0.20 0.60

MILLIMETERS

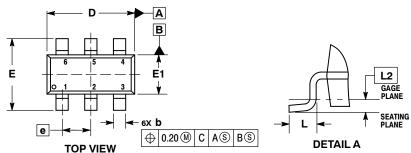
MIN MAX

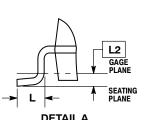
0.00

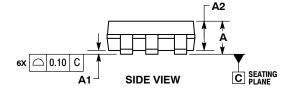
0.90 A2

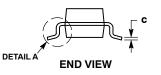
0.08

2.70 D









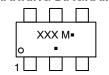
GENERIC MARKING DIAGRAM*

NOTES:

A A1

b

E1



XXX = Specific Device Code

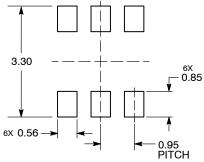
Μ = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " •", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.